

ABSTRACT

The purpose of the present invention is to propose a high strength solder alloy which has a stronger mechanical strength and an excellent wetness property.

- 5 The high strength solder alloy according to the present invention is characterized in that it comprises Si of 0.0005 to 0.35 wt.%, Ag of 0 to 5.0 wt.%, Sb of 0 to 10.0 wt.%, Bi of 0 to 10.0 wt.%, Sn of 20 to 95 wt.%, Pb of 0 to 70 wt.% and Ca of 0 to 0.5 wt.%.

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